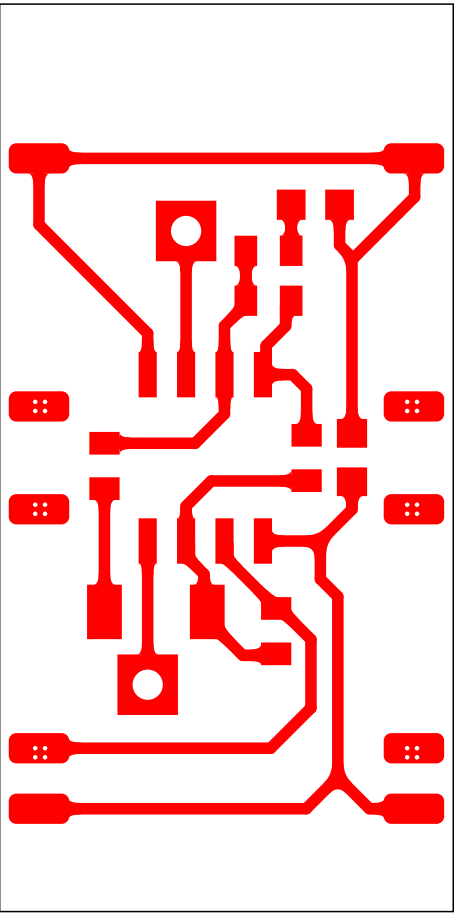
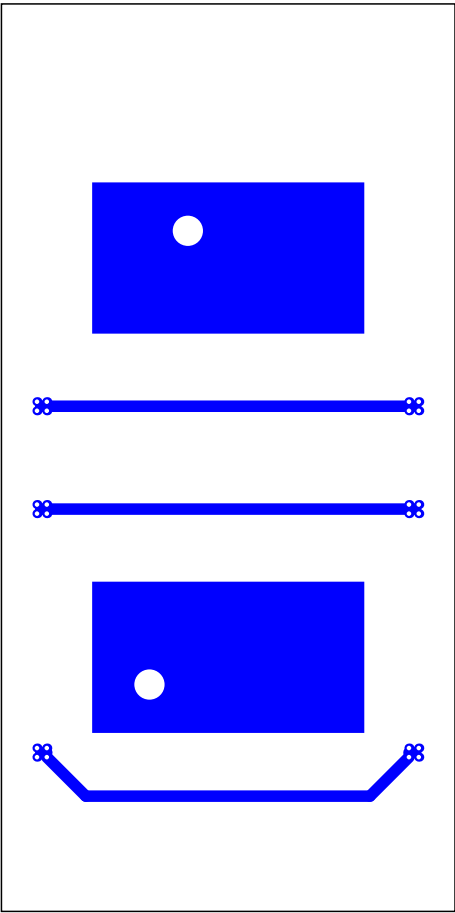


SEMG Sensor

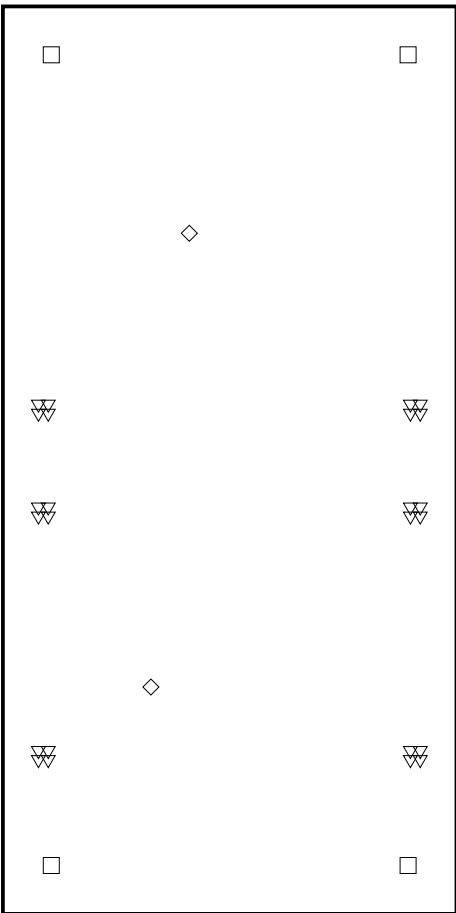
Top Layer (Scale 4:1)



Bottom Layer (Scale 4:1)



Drill Drawing View (Scale 4:1)



Drill Table

Symbol	Count	Hole Size	Plated	Hole Tolerance
▽	24	0.15mm	Plated	
◇	2	1.00mm	Plated	
□	4	2.00mm	Non-Plated	
30 Total				

Layer Stack Legend

	Material	Layer	Thickness	Dielectric Material	Type	Gerber
		Top Overlay			Legend	GTO
		Top Solder	0.01mm	Solder Resist	Solder Mask	GTS
	Copper	Top Layer	0.04mm		Signal	GTL
	Core		1.50mm	Core-043	Dielectric	
	Copper	Bottom Layer	0.04mm		Signal	GBL
	Surface Material	Bottom Solder	0.01mm	Solder Resist	Solder Mask	GBS
		Bottom Overlay			Legend	GBO

Total thickness: 1.59mm



WF TECNOLOGIA

Projeto de PCB's
+55 41 99558-4388
eng.figueiredo@outlook.com.br

Projeto **SEMG Sensor**

Elaboração **Marlio**

Código **=Codigo**

Data **05/11/2024**

Arquivo **E:\WF_Tecnologia\Roger_Lakoski_Mestrado\RL_Sensor_Proteses\Sensor_Proteses_Fabrication.PCBDwf**

Aprovação **Roger**

Revisão **R01**

Horário **23:04**

Layout **Natan**

Folha **1/1**

Tamanho **A3**

Revisão

Data

Responsável

Histórico

R00

03/11/2022

Natan MF

=HIST01

R01

05/04/2022

Natan MF

=HIST02

R02

04/11/2022

Natan MF

=HIST03